EXHIBIT 2 FILED UNDER SEAL

Case 2:22-cv-00203-JRG-RSP Document 328-3 Filed 12/05/23 Page 2 of 5 PageID #:

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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
13/288,850	11/03/2011	Hyun Lee	NETL.071A	2466
	7590 10/11/201 e of Jamie Zheng, Ph.D	EXAMINER		
P.O. Box 60573			HOANG, HUAN	
Palo Alto, CA 94306			ART UNIT	PAPER NUMBER
			2827	
			NOTIFICATION DATE	DELIVERY MODE
			10/11/2013	ELECTRONIC

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

jz@jzpatent.com

Case 2:22-cv-00203-JRG-RSP Docume	ent 328-3 Filed 12/05/23	Page 3 of	5 PageID #:			
	Application No. Applicant(s) 13/288,850 LEE, HYUN		s)			
Office Action Summary	Examiner HUAN HOANG	Art Unit 2827	AIA (First Inventor to File) Status No			
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the o	orresponder	nce address			
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tir vill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. mely filed the mailing date ED (35 U.S.C. § 1	of this communication. 33).			
Status						
1) Responsive to communication(s) filed on A declaration(s)/affidavit(s) under 37 CFR 1.1						
, <u> </u>	action is non-final.					
· · · · · · · · · · · · · · · · · · ·	,—					
; the restriction requirement and election have been incorporated into this action. 4) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims						
5) Solum(s) 1-34 is/are pending in the application. 5a) Of the above claim(s) is/are withdraw 6) Claim(s) is/are allowed. 7) Claim(s) 1-7,9-21 and 23-34 is/are rejected. 8) Claim(s) 8 and 22 is/are objected to. 9) Claim(s) are subject to restriction and/or If any claims have been determined allowable, you may be eliparticipating intellectual property office for the corresponding aphttp://www.uspto.gov/patents/init_events/pph/index.jsp or send Application Papers 10) The specification is objected to by the Examined 11) The drawing(s) filed on 11/03/11 is/are: a) and application above the corresponding aphttp://www.uspto.gov/patents/init_events/pph/index.jsp or send	vn from consideration. relection requirement. igible to benefit from the Patent Pro polication. For more information, plea an inquiry to PPHfeedback@uspto.e	ase see gov.				
Applicant may not request that any objection to the one of the correction and the correction are the corrections.	= ' '					
Priority under 35 U.S.C. § 119 12) Acknowledgment is made of a claim for foreign Certified copies: a) All b) Some * c) None of the: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Applica rity documents have been receiv I (PCT Rule 17.2(a)).	tion No				
Attachment(s) 1) X Notice of References Cited (PTO-892)	3) 🔲 Interview Summary	, (PTO-412\				
2) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date 05/23/12, 04/25/13.	3)					

Application/Control Number: 13/288,850

Page 4

Art Unit: 2827

plurality of array dies; and the second data conduit upon the second load is less than a load that would be on the second data conduit upon the second die interconnect being placed in electrical communication with at least one data port of each of the array dies of the plurality of array dies." is confusing since the first die interconnect/the second die interconnect is only in electrical communication with the first group of array dies/the second group of at least one die; therefore, the first die interconnect/the second die interconnect cannot be in electrical communication with each of the array dies (at least one array die of the second group is not in electrical communication with the first die interconnect and the array dies of the first group are not in electrical communication with the second die interconnect).

Claim Rejections - 35 USC § 102

7. The following is a quotation of the appropriate paragraphs of pre-AIA 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 8. Claims 1-4, 7, 9-13, 15-21, 23, 24, 27-29, 31, 33 and 34 are rejected under pre-AIA 35 U.S.C. 102(b) as being anticipated by Rajan et al. (US 2008/0025137).

Regarding claim 1: Rajan (Fig. 2B) shows a memory package, comprising:

a plurality of input/output terminals (address, Control, Clock and Data) via which the memory package communicate data and control/address signals with one or more external devices;

Page 5

Application/Control Number: 13/288,850

Art Unit: 2827

a plurality of stacked array dies (paragraph [0043], lines 1-3) including a first group of array dies (206A and 206C) and a second group (206B and 206D) of at least one array die, each array die having data ports;

at least a first die interconnect (Data connected to 206A and 206C) and a second die interconnect (Data connected to 206B and 206D), the first die interconnect in electrical communication with first group of array dies and not in electrical communication with the second group of at least one array die, the second die interconnect in electrical communication with the second group of at least one array die and not in electrical communication with the first group of array dies; and

a control die (BUFFER CHIP) comprising at least a first data conduit between the first die interconnect and a first terminal (Data) of the plurality of input/output terminals, and at least a second data conduit between the second die interconnect and the first terminal, the first terminal being a data terminal, the control die further comprising a control circuit (paragraph [0044], lines 5-7) to control respective states of the first data conduit and the second data conduit in response to control signals received via one or more second terminals of the plurality of terminals (Address, Clock and Control).

Regarding claims 2-4: Rajan discloses the memory package of claim 1, wherein the control signals include data path control signals (Control, Address and Clock must be used to address the DRAM circuits and control the data between Data terminal to DRAM circuits) for controlling the first and second data conduits.